

PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING
MICROELECTRONIC IMAGERS

ABSTRACT OF THE DISCLOSURE

A microelectronic imager comprising an imaging unit and an optics unit attached to the imaging unit, and methods for packaging microelectronic imagers. In one embodiment, the imaging unit can include (a) a microelectronic die with an image sensor and a plurality of external contacts electrically coupled to the image sensor and (b) a first referencing element fixed to the imaging unit. The optics unit can include an optic member and a second referencing element fixed to the optics unit. The second referencing element is seated with the first referencing element at a fixed, preset position in which the optic member is situated at a desired location relative to the image sensor.